

Tool ID: 301  
Tool Location: 103

Equipment Information Sheet  
Oxford ALD FlexAL

Manager: Jeremy Clark  
Backup: Mac McMurdy

607-254-6487  
607-254-4813

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- The FlexAL ALD tool uses toxic and highly reactive/pyrophoric precursors for film deposition. Materials are monitored by the Toxic Gas Monitoring and Control System that will sound a gas alarm in the event of a detection.

USAGE RESTRICTIONS

- Run the recipe "3min end of use clean" once you are finished processing.
- Discuss films thicker than 50nm with the tool manager.

SCHEDULING/SIGN-UP RESTRICTIONS

- None

Minimum Tool Time: 60 minutes

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds	
Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compoundsare materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Full size 100mm wafers (other wafer sizes up to 200mm can be accommodated with staff assistance).
- Pieces can be processed with the use of a carrier plate.
- Polymers and resist need to be fully cured and only run using 110C processes
- Changes to recipes other than loop count must be cleared with tool managers

Last Updated: 08/18/2023